



Material declaration form

General Information			
IPC	1752	Version	2
Form type*	Distribute		
Sectionals*	Material information	Subsectionals*	A-D
	Manufacturing information		*: Required Field

Supplier Information			
Company name*	STMicroelectronics	Response Date*	2024-07-15
Contact name*	Refer to Supplier Comment section		Refer to Supplier Comment section
Contact phone*	Refer to Supplier Comment section	Contact email*	Refer to Supplier Comment section
Authorized representative*	MDG CHAMPION	Representative title	MDGMaterial Declaration champion
Representative phone*	Refer to Supplier Comment section	Representative email*	Refer to Supplier Comment section
Supplier comment	Online Technical Support - STMicroelectronics : http://www.st.com/web/en/support/support.html		

Uncertainty statement

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Legal statement

Supplier acceptance*	true	Legal declaration*	Standard
Supplier certifies that it gathered the provided information and such information is true and correct to the best of its knowledge and belief, as of the date that Supplier completes this form. Supplier acknowledges that Company will rely on this certification in determining the compliance of its products. Company acknowledges that Supplier may have relied on information provided by others in completing this form, and that Supplier may not have independently verified such information. However, in situations where Supplier has not independently verified information provided by others, Supplier agrees that, at a minimum, its suppliers have provided certifications regarding their contributions to the part(s), and those certifications are at least as comprehensive as the certification in this paragraph. If the Company and the Supplier enter into a written agreement with respect to the identified part(s), the terms and conditions of that agreement, including any warranty rights and/or remedies provided as part of that agreement, will be the sole and exclusive source of the Supplier's liability and the Company's remedies for issues that arise regarding information the Supplier provides in this form.			



Product				
Mfr item number	Mfr item name	Version	Manufacturing site	date
STM32C051G8U6	70MB*44CXXXA	A	998Z	2024-07-15
Amount	Unit of measure	Unit type	ST ECOPACK grade	
24	mg	Each	ECOPACK® 2	

Manufacturing information				
J-STD-020 MSL rating	Classification temperature	Number of reflow cycles		
3	260	3		
Bulk solder termination	Terminal plating	Terminal base alloy	Comment	
Not Applicable	Nickel/Palladium/Gold (Ni/Pd/Au)	Copper Alloy	0	
Package designator	Package size	Number of instances	Shape	
QFN	4x4	28	Flat	
Comment	Package : A0B0 UFQFPN 4X4X0.55 28L PITCH0.5 COL 8202209			

QueryList : RoHS Directive 2011/65/EU- 8 June 2011 – Annex II amended by Delegated Directive 2015/863 - 31 March 2015		Response
1 - Product(s) meets EU RoHS requirement without any exemptions		true
2 - Product(s) meets EU RoHS requirements except lead in solder and this usage may qualify under the lead in solder '7b' exemption (other selected exemptions may apply)		false
3 - Product(s) meets EU RoHS requirements by application of the selected exemption(s)		false
4 - Product(s) does not meet EU RoHS requirements and is not under exemptions		false
Exemption Id.	Description	
,		

QueryList : REACH-27th June 2024				Response
QUERY				Response
1 - Product(s) does not contain REACH Substances Of Very High Concern above the limits per the definition within REACH				true
CategoryLevel_Name	CategoryLevel_Threshold	amount in product (mg)	Application	ppm in product
,	0			



Material Composition Declaration : note : Substance present with less 0.001mg will not be declared in this document						Mfr Item Name	70MB*44CXXXA		24.0097		5000000.0	1000000.0				
Homogeneous material	Material group	Mass	Unit of measure	Level	Substance category	Substance	CAS	Exempt	Mass	Unit of measure	Concentration in homogeneous material (ppm)	Concentration in product (ppm)				
Die or dies	M-011 Other inorganic materials	1.238	mg	supplier	die	Silicon (Si)	7440-21-3		1.128	mg	911738	46992				
				supplier	metallization	Aluminium (Al)	7429-90-5		0.005	mg	4032	208				
				supplier	metallization	Copper (Cu)	7440-50-8		0.047	mg	37634	1940				
				supplier	metallization	Tantalum (Ta)	7440-25-7		0.015	mg	12097	623				
				supplier	metallization	Titanium (Ti)	7440-32-6		0.001	mg	448	23				
				supplier	metallization	Tungsten (W)	7440-33-7		0.001	mg	448	23				
				supplier	Passivation	Silicon Nitride	12033-89-5		0.012	mg	9409	485				
				supplier	Passivation	Silicon Oxide	7631-86-9		0.030	mg	24194	1247				
				DAF (HR-5104)	M-011 Other inorganic materials	0.113	mg	supplier	Epoxy Resin	Epoxy Resin A	Proprietary		0.011	mg	95238	449
								supplier	Epoxy Resin	Epoxy Resin B	Proprietary		0.016	mg	142857	673
supplier	Epoxy Resin	Phenol Resin	Proprietary						0.016	mg	142857	673				
supplier	Plastics/polymers	SiO2 Filler	Proprietary						0.054	mg	476190	2243				
supplier	Epoxy Resin	(Meta)Acrylic Copolymer	Proprietary						0.016	mg	142857	673				
Encapsulation (EME-G770HCD)	M-011 Other inorganic materials	11.475	mg	supplier	Epoxy Resin	Epoxy Resin	Proprietary		0.339	mg	29542	14119				
				supplier	Plastics/polymers	Phenol Resin	Proprietary		0.339	mg	29542	14119				
				supplier	Plastics/polymers	Silica (Amorphous) A	60676-86-0		9.040	mg	787789	376502				
				supplier	Plastics/polymers	Silica (Amorphous) B	7631-86-9		1.695	mg	147710	70594				
				supplier	Additives	Carbon Black	1333-86-4		0.062	mg	5416	2588				
Bonding Wire (Au)	Bonding Wire	0.240	mg	supplier	Metals	Gold (Au)	7440-57-5		0.240	mg	999480	10005				
				supplier	Metals	Palladium (Pd)	7440-05-3		0.000	mg	520	5				
Leadframe (C7025 + NiPdAu)	Copper & its alloys	10.944	mg	supplier	Metals	Nickel (Ni)	7440-02-0		0.485	mg	44305	20195				
				supplier	Glass	Silicon (Si)	7440-21-3		0.078	mg	7125	3248				
				supplier	Metals	Magnesium (Mg)	7439-95-4		0.019	mg	1720	784				
				supplier	Metals	Silver (Ag)	7440-22-4		0.002	mg	215	98				
				supplier	Metals	Copper (Cu)	7440-50-8		10.351	mg	945850	431133				
				supplier	Metals	Palladium (Pd)	7440-05-3		0.005	mg	490	223				
				supplier	Metals	Gold (Au)	7440-57-5		0.003	mg	295	134				